# SECTION C — CHEMISTRY; METALLURGY

COATING METALLIC MATERIAL; COATING MATERIAL WITH METALLIC MATERIAL; CHEMICAL SURFACE TREATMENT; DIFFUSION TREATMENT OF METALLIC MATERIAL; COATING BY VACUUM EVAPORATION, BY SPUTTERING, BY ION IMPLANTATION OR BY CHEMICAL VAPOUR DEPOSITION, IN GENERAL; INHIBITING CORROSION OF METALLIC MATERIAL OR INCRUSTATION IN GENERAL

### Note(s) [4]

- 1. In this class, the following expression is used with the meaning indicated:
  - "metallic material" covers:
    - a. metals;
    - b. alloys.
- 2. Attention is drawn to the Note following the title of subclass C22C.
- COATING METALLIC MATERIAL; COATING MATERIAL WITH METALLIC MATERIAL; SURFACE TREATMENT OF METALLIC MATERIAL BY DIFFUSION INTO THE SURFACE, BY CHEMICAL CONVERSION OR SUBSTITUTION; COATING BY VACUUM EVAPORATION, BY SPUTTERING, BY ION IMPLANTATION OR BY CHEMICAL VAPOUR DEPOSITION, IN GENERAL (making metal-coated products by extrusion B21C 23/22; covering with metal by connecting pre-existing layers to articles, see the relevant places, e.g. B21D 39/00, B23K; metallising of glass C03C; metallising mortars, concrete, artificial stone, ceramics or natural stone C04B 41/00; enamelling of, or applying a vitreous layer to, metals C23D; treating metal surfaces or coating of metals by electrolysis or electrophoresis C25D; single-crystal film growth C30B; by metallising textiles D06M 11/83; decorating textiles by locally metallising D06Q 1/04) [4]

## Note(s) [4]

In this subclass, an operation is considered as pretreatment or after-treatment when it is specially adapted for, but quite distinct from, the coating process concerned and constitutes an independent operation. If an operation results in the formation of a permanent sub- or upper layer, it is not considered as pretreatment or after-treatment and is classified as a multi-coating process.

## Subclass index

COATING USING MOLTEN COATING MATERIAL	2/00-6/00
SOLID STATE DIFFUSION COATING	
COATING BY VACUUM EVAPORATION, SPUTTERING OR ION-IMPLANTATION	14/00
CHEMICAL COATING	16/00-20/00
CONTACT PLATING	18/00
CHEMICAL SURFACE TREATMENT	22/00
COATING USING INORGANIC POWDER	24/00
OTHER COATING, MULTI-LAYER COATING	26/00, 28/00
COMPOSITION OF METALLIC COATING MATERIAL	

## Coating by applying the coating material in the molten state [4]

- 2/00 Hot-dipping or immersion processes for applying the coating material in the molten state without affecting the shape; Apparatus therefor [4, 2006.01]
- Pretreatment of the material to be coated, e.g. for coating on selected surface areas (C23C 2/30 takes precedence) [4, 2006.01]
- characterised by the coating material **[4, 2006.01]**
- 2/06 Zinc or cadmium or alloys based thereon **[4, 2006.01]**
- 2/08 • Tin or alloys based thereon **[4, 2006.01]**
- 2/10 • Lead or alloys based thereon **[4, 2006.01]**
- 2/12 • Aluminium or alloys based thereon [4, 2006.01]

- Removing excess of molten coatings; Controlling or regulating the coating thickness [4, 2006.01]
- 2/16 using fluids under pressure, e.g. air knives [4, 2006.01]
- 2/18 • Removing excess of molten coatings from elongated material [4, 2006.01]
- 2/20 • Strips; Plates **[4, 2006.01]**
- 2/22 by rubbing, e.g. using knives **[4, 2006.01]**
- 2/24 using magnetic or electric fields [4, 2006.01]
- 2/26 After-treatment (C23C 2/14 takes precedence) **[4, 2006.01]**
- 2/28 Thermal after-treatment, e.g. treatment in oil bath [4, 2006.01]

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2/30	<ul> <li>Fluxes or coverings on molten baths (C23C 2/22 takes precedence) [4, 2006.01]</li> </ul>	8/12	• • • using elemental oxygen or ozone [4, 2006.01]
2/32	<ul> <li>using vibratory energy applied to the bath or</li> </ul>	8/14	• • • • • • Oxidising of ferrous surfaces [4, 2006.01]
	substrate (C23C 2/14 takes precedence) [4, 2006.01]	8/16	• • • using oxygen-containing compounds, e.g.
2/34	• characterised by the shape of the material to be	0./40	H <sub>2</sub> O, CO <sub>2</sub> [4, 2006.01]
2/20	treated (C23C 2/14 takes precedence) [4, 2006.01]	8/18	• • • • Oxidising of ferrous surfaces [4, 2006.01]
2/36	• Elongated material [4, 2006.01]	8/20	• • • Carburising [4, 2006.01]
2/38	• • Wires; Tubes [4, 2006.01]	8/22	• • • of ferrous surfaces [4, 2006.01]
2/40	• • • Plates; Strips [4, 2006.01]	8/24	• • • Nitriding [4, 2006.01]
4/00	Coating by spraying the coating material in the	8/26	• • • of ferrous surfaces [4, 2006.01]
	molten state, e.g. by flame, plasma or electric	8/28	• • more than one element being applied in one
	discharge (build-up welding B23K, e.g. B23K 5/18,	0./20	step [4, 2006.01]
	B23K 9/04) <b>[4, 2006.01, 2016.01]</b>	8/30	• • • Carbo-nitriding [4, 2006.01]
4/01	<ul> <li>Selective coating, e.g. pattern coating, without pre-</li> </ul>	8/32	• • • • of ferrous surfaces [4, 2006.01]
	treatment of the material to be coated [2016.01]	8/34	<ul> <li>more than one element being applied in more than one step [4, 2006.01]</li> </ul>
4/02	• Pretreatment of the material to be coated, e.g. for	8/36	<ul> <li>using ionised gases, e.g. ionitriding [4, 2006.01]</li> </ul>
4.10.4	coating on selected surface areas [4, 2006.01]	8/38	• • • Treatment of ferrous surfaces [4, 2006.01]
4/04	• characterised by the coating material [4, 2006.01]	8/40	• using liquids, e.g. salt baths, liquid
4/06	• • Metallic material [4, 2006.01, 2016.01]	0/40	suspensions [4, 2006.01]
4/067	• • containing free particles of non-metal elements,	8/42	<ul> <li>only one element being applied [4, 2006.01]</li> </ul>
	e.g. carbon, silicon, boron, phosphorus or arsenic [2016.01]	8/44	<ul> <li>Carburising [4, 2006.01]</li> </ul>
4/073	• • containing MCrAl or MCrAlY alloys, where M	8/46	• • • • of ferrous surfaces [4, 2006.01]
4/0/3	is nickel, cobalt or iron, with or without non-	8/48	• • • Nitriding [4, 2006.01]
	metal elements [2016.01]	8/50	• • • • of ferrous surfaces [4, 2006.01]
4/08	containing only metal elements	8/52	more than one element being applied in one
., 00	(C23C 4/073 takes	0/32	step [4, 2006.01]
	precedence) [4, 2006.01, 2016.01]	8/54	• • • Carbo-nitriding [4, 2006.01]
4/10	<ul> <li>Oxides, borides, carbides, nitrides or silicides;</li> </ul>	8/56	• • • • of ferrous surfaces [4, 2006.01]
	Mixtures thereof [4, 2006.01, 2016.01]	8/58	<ul> <li>more than one element being applied in more than</li> </ul>
4/11	• • • Oxides [2016.01]	0,00	one step [4, 2006.01]
4/12	<ul> <li>characterised by the method of</li> </ul>	8/60	<ul> <li>using solids, e.g. powders, pastes (using liquid</li> </ul>
	spraying <b>[4, 2006.01, 2016.01]</b>		suspensions of solids C23C 8/40) <b>[4, 2006.01]</b>
4/123	• • Spraying molten metal [2016.01]	8/62	<ul> <li>only one element being applied [4, 2006.01]</li> </ul>
4/126	<ul> <li>Detonation spraying [2016.01]</li> </ul>	8/64	• • • Carburising [4, 2006.01]
4/129	<ul> <li>Flame spraying [2016.01]</li> </ul>	8/66	• • • of ferrous surfaces [4, 2006.01]
4/131	<ul> <li>Wire arc spraying [2016.01]</li> </ul>	8/68	• • • Boronising [4, 2006.01]
4/134	• • Plasma spraying <b>[2016.01]</b>	8/70	• • • of ferrous surfaces [4, 2006.01]
4/137	<ul> <li>Spraying in vacuum or in an inert</li> </ul>	8/72	<ul> <li>more than one element being applied in one</li> </ul>
	atmosphere [2016.01]		step <b>[4, 2006.01]</b>
4/14	for coating elongate	8/74	• • • Carbo-nitriding [4, 2006.01]
4.446	material [4, 2006.01, 2016.01]	8/76	• • • of ferrous surfaces <b>[4, 2006.01]</b>
4/16	• • • Wires; Tubes [4, 2006.01, 2016.01]	8/78	• • more than one element being applied in more than
4/18	• After-treatment [4, 2006.01]		one step <b>[4, 2006.01]</b>
6/00	Coating by casting molten material on the	8/80	• After-treatment [4, 2006.01]
0/00	substrate [4, 2006.01]	40400	
	54554446 [1, 455562]	10/00	Solid state diffusion of only metal elements or silicon
		10/02	into metallic material surfaces [4, 2006.01]
olid stat	e diffusion into metallic material surfaces [4]	10/02	• Pretreatment of the material to be coated
0.400		10/04	(C23C 10/04 takes precedence) [4, 2006.01]
8/00	Solid state diffusion of only non-metal elements into	10/04	<ul> <li>Diffusion into selected surface areas, e.g. using masks [4, 2006.01]</li> </ul>
	metallic material surfaces (diffusion of silicon C23C 10/00); Chemical surface treatment of metallic	10/06	• using gases [4, 2006.01]
	material by reaction of the surface with a reactive	10/08	<ul> <li>only one element being diffused [4, 2006.01]</li> </ul>
	gas, leaving reaction products of surface material in	10/00	• • • Chromising [4, 2006.01]
	the coating, e.g. conversion coatings, passivation of	10/10	• • • • of ferrous surfaces [4, 2006.01]
	metals (C23C 14/00 takes precedence) [4, 2006.01]	10/12	<ul> <li>more than one element being diffused in one</li> </ul>
8/02	<ul> <li>Pretreatment of the material to be coated (C23C 8/04</li> </ul>	10/14	step [4, 2006.01]
	takes precedence) [4, 2006.01]	10/16	<ul> <li>more than one element being diffused in more than</li> </ul>
8/04	<ul> <li>Treatment of selected surface areas, e.g. using</li> </ul>	10/10	one step [4, 2006.01]
	masks <b>[4, 2006.01]</b>	10/18	• using liquids, e.g. salt baths, liquid
8/06	• using gases [4, 2006.01]	10/10	suspensions [4, 2006.01]
8/08	<ul> <li>only one element being applied [4, 2006.01]</li> </ul>	10/20	<ul> <li>only one element being diffused [4, 2006.01]</li> </ul>
8/10	• • • Oxidising [4, 2006.01]	10/22	• • • Metal melt containing the element to be
			diffused <b>[4, 2006.01]</b>

			C23C
10/24	• • • Salt bath containing the element to be diffused [4, 2006.01]	14/32	• • by explosion; by evaporation and subsequent ionisation of the vapours (C23C 14/34-
10/26	• • more than one element being diffused [4, 2006.01]	14/24	C23C 14/48 take precedence) [4, 2006.01]
10/28	• using solids, e.g. powders, pastes [4, 2006.01]	14/34	• • Sputtering [4, 2006.01]
10/30	<ul> <li>using a layer of powder or paste on the surface (using liquid suspensions of solids C23C 10/18) [4, 2006.01]</li> </ul>	14/35 14/36	<ul> <li>• by application of a magnetic field, e.g. magnetron sputtering [5, 2006.01]</li> <li>• Diode sputtering (C23C 14/35 takes</li> </ul>
10/32	• • • Chromising [4, 2006.01]	- 1, 00	precedence) [4, 5, 2006.01]
10/34	Embedding in a powder mixture, i.e. pack	14/38	• • • by direct current glow discharge [4, 2006.01]
10/36	cementation <b>[4, 2006.01]</b> • • • only one element being diffused <b>[4, 2006.01]</b>	14/40	• • • with alternating current discharge, e.g. high-frequency discharge [4, 2006.01]
10/38 10/40	<ul> <li>• • • Chromising [4, 2006.01]</li> <li>• • • of ferrous surfaces [4, 2006.01]</li> </ul>	14/42	• • • Triode sputtering (C23C 14/35 takes precedence) <b>[4, 5, 2006.01]</b>
10/42	• • • • • in the presence of volatile transport additives, e.g. halogenated	14/44	• • • by application of high frequencies and additional direct voltages [4, 2006.01]
10/44	substances [4, 2006.01]  • • • • Siliconising [4, 2006.01]	14/46	• • • by ion beam produced by an external ion source (C23C 14/40 takes precedence) [4, 2006.01]
10/46	• • • • • of ferrous surfaces [4, 2006.01]	14/48	• • Ion implantation [4, 2006.01]
10/48	• • • • Aluminising [4, 2006.01]	14/50	• • Substrate holders [4, 2006.01]
10/50 10/52	<ul> <li>• • • of ferrous surfaces [4, 2006.01]</li> <li>• more than one element being diffused in one</li> </ul>	14/52	<ul> <li>Means for observation of the coating process [4, 2006.01]</li> </ul>
10/54	step [4, 2006.01]  • • • Diffusion of at least chromium [4, 2006.01]	14/54	<ul> <li>Controlling or regulating the coating process [4, 2006.01]</li> </ul>
10/56	• • • • • and at least aluminium [4, 2006.01]	14/56	<ul> <li>Apparatus specially adapted for continuous</li> </ul>
10/58	<ul> <li>more than one element being diffused in more than one step [4, 2006.01]</li> </ul>		coating; Arrangements for maintaining the vacuum, e.g. vacuum locks [4, 2006.01]
10/60	• After-treatment [4, 2006.01]	14/58	• After-treatment [4, 2006.01]
12/00	Solid state diffusion of at least one non-metal element other than silicon and at least one metal element or silicon into metallic material surfaces [4, 2006.01]	Chemica plating [4	l deposition or plating by decomposition; Contact 4
<b>12/00</b> 12/02	other than silicon and at least one metal element or		Chemical coating by decomposition of gaseous compounds, without leaving reaction products of
12/02	<ul> <li>other than silicon and at least one metal element or silicon into metallic material surfaces [4, 2006.01]</li> <li>Diffusion in one step [4, 2006.01]</li> <li>by vacuum evaporation, by sputtering or by ion</li> </ul>	plating [4	Chemical coating by decomposition of gaseous compounds, without leaving reaction products of surface material in the coating, i.e. chemical vapour deposition [CVD] processes (reactive sputtering or vacuum evaporation C23C 14/00) [4, 2006.01]
12/02 <u>Coating</u>	other than silicon and at least one metal element or silicon into metallic material surfaces [4, 2006.01]  • Diffusion in one step [4, 2006.01]  by vacuum evaporation, by sputtering or by ion tion [4]  Coating by vacuum evaporation, by sputtering or by	plating [4	Chemical coating by decomposition of gaseous compounds, without leaving reaction products of surface material in the coating, i.e. chemical vapour deposition [CVD] processes (reactive sputtering or
12/02  Coating limplanta	other than silicon and at least one metal element or silicon into metallic material surfaces [4, 2006.01]  • Diffusion in one step [4, 2006.01]  by vacuum evaporation, by sputtering or by ion tion [4]	plating [4	Chemical coating by decomposition of gaseous compounds, without leaving reaction products of surface material in the coating, i.e. chemical vapour deposition [CVD] processes (reactive sputtering or vacuum evaporation C23C 14/00) [4, 2006.01]  on temporary substrates, e.g. on substrates
12/02 Coating implanta 14/00	other than silicon and at least one metal element or silicon into metallic material surfaces [4, 2006.01]  • Diffusion in one step [4, 2006.01]  by vacuum evaporation, by sputtering or by ion tion [4]  Coating by vacuum evaporation, by sputtering or by ion implantation of the coating forming material [4, 2006.01]	<b>plating [</b> 4 <b>16/00</b> 16/01	Chemical coating by decomposition of gaseous compounds, without leaving reaction products of surface material in the coating, i.e. chemical vapour deposition [CVD] processes (reactive sputtering or vacuum evaporation C23C 14/00) [4, 2006.01]  on temporary substrates, e.g. on substrates subsequently removed by etching [7, 2006.01]  Pretreatment of the material to be coated
12/02  Coating implanta  14/00	other than silicon and at least one metal element or silicon into metallic material surfaces [4, 2006.01]  • Diffusion in one step [4, 2006.01]  by vacuum evaporation, by sputtering or by ion tion [4]  Coating by vacuum evaporation, by sputtering or by ion implantation of the coating forming material [4, 2006.01]  • Pretreatment of the material to be coated (C23C 14/04 takes precedence) [4, 2006.01]	<b>plating [</b> 4 <b>16/00</b> 16/01 16/02	Chemical coating by decomposition of gaseous compounds, without leaving reaction products of surface material in the coating, i.e. chemical vapour deposition [CVD] processes (reactive sputtering or vacuum evaporation C23C 14/00) [4, 2006.01]  on temporary substrates, e.g. on substrates subsequently removed by etching [7, 2006.01]  Pretreatment of the material to be coated (C23C 16/04 takes precedence) [4, 2006.01]  Coating on selected surface areas, e.g. using
12/02 Coating implanta 14/00	other than silicon and at least one metal element or silicon into metallic material surfaces [4, 2006.01]  • Diffusion in one step [4, 2006.01]  by vacuum evaporation, by sputtering or by ion tion [4]  Coating by vacuum evaporation, by sputtering or by ion implantation of the coating forming material [4, 2006.01]  • Pretreatment of the material to be coated (C23C 14/04 takes precedence) [4, 2006.01]  • Coating on selected surface areas, e.g. using	16/00 16/01 16/02 16/04	Chemical coating by decomposition of gaseous compounds, without leaving reaction products of surface material in the coating, i.e. chemical vapour deposition [CVD] processes (reactive sputtering or vacuum evaporation C23C 14/00) [4, 2006.01]  on temporary substrates, e.g. on substrates subsequently removed by etching [7, 2006.01]  Pretreatment of the material to be coated (C23C 16/04 takes precedence) [4, 2006.01]  Coating on selected surface areas, e.g. using masks [4, 2006.01]  characterised by the deposition of metallic
12/02  Coating implanta  14/00	other than silicon and at least one metal element or silicon into metallic material surfaces [4, 2006.01]  • Diffusion in one step [4, 2006.01]  by vacuum evaporation, by sputtering or by ion tion [4]  Coating by vacuum evaporation, by sputtering or by ion implantation of the coating forming material [4, 2006.01]  • Pretreatment of the material to be coated (C23C 14/04 takes precedence) [4, 2006.01]	16/00 16/01 16/02 16/04 16/06	Chemical coating by decomposition of gaseous compounds, without leaving reaction products of surface material in the coating, i.e. chemical vapour deposition [CVD] processes (reactive sputtering or vacuum evaporation C23C 14/00) [4, 2006.01]  on temporary substrates, e.g. on substrates subsequently removed by etching [7, 2006.01]  Pretreatment of the material to be coated (C23C 16/04 takes precedence) [4, 2006.01]  Coating on selected surface areas, e.g. using masks [4, 2006.01]  characterised by the deposition of metallic material [4, 2006.01]  from metal halides [4, 2006.01]
12/02  Coating implanta  14/00  14/02  14/04	other than silicon and at least one metal element or silicon into metallic material surfaces [4, 2006.01]  • Diffusion in one step [4, 2006.01]  by vacuum evaporation, by sputtering or by ion tion [4]  Coating by vacuum evaporation, by sputtering or by ion implantation of the coating forming material [4, 2006.01]  • Pretreatment of the material to be coated (C23C 14/04 takes precedence) [4, 2006.01]  • Coating on selected surface areas, e.g. using masks [4, 2006.01]	16/00 16/01 16/02 16/04 16/06 16/08	Chemical coating by decomposition of gaseous compounds, without leaving reaction products of surface material in the coating, i.e. chemical vapour deposition [CVD] processes (reactive sputtering or vacuum evaporation C23C 14/00) [4, 2006.01]  on temporary substrates, e.g. on substrates subsequently removed by etching [7, 2006.01]  Pretreatment of the material to be coated (C23C 16/04 takes precedence) [4, 2006.01]  Coating on selected surface areas, e.g. using masks [4, 2006.01]  characterised by the deposition of metallic material [4, 2006.01]  from metal halides [4, 2006.01]  peposition of chromium only [4, 2006.01]
12/02  Coating implanta  14/00  14/02  14/04	other than silicon and at least one metal element or silicon into metallic material surfaces [4, 2006.01]  • Diffusion in one step [4, 2006.01]  by vacuum evaporation, by sputtering or by ion tion [4]  Coating by vacuum evaporation, by sputtering or by ion implantation of the coating forming material [4, 2006.01]  • Pretreatment of the material to be coated (C23C 14/04 takes precedence) [4, 2006.01]  • Coating on selected surface areas, e.g. using masks [4, 2006.01]  • characterised by the coating material (C23C 14/04	16/00 16/00 16/01 16/02 16/04 16/06 16/08 16/10 16/12 16/14	Chemical coating by decomposition of gaseous compounds, without leaving reaction products of surface material in the coating, i.e. chemical vapour deposition [CVD] processes (reactive sputtering or vacuum evaporation C23C 14/00) [4, 2006.01]  on temporary substrates, e.g. on substrates subsequently removed by etching [7, 2006.01]  Pretreatment of the material to be coated (C23C 16/04 takes precedence) [4, 2006.01]  Coating on selected surface areas, e.g. using masks [4, 2006.01]  characterised by the deposition of metallic material [4, 2006.01]  from metal halides [4, 2006.01]  from composition of chromium only [4, 2006.01]  Deposition of aluminium only [4, 2006.01]  Deposition of only one other metal element [4, 2006.01]
12/02  Coating implanta 14/00  14/02 14/04 14/06	other than silicon and at least one metal element or silicon into metallic material surfaces [4, 2006.01]  • Diffusion in one step [4, 2006.01]  by vacuum evaporation, by sputtering or by ion tion [4]  Coating by vacuum evaporation, by sputtering or by ion implantation of the coating forming material [4, 2006.01]  • Pretreatment of the material to be coated (C23C 14/04 takes precedence) [4, 2006.01]  • Coating on selected surface areas, e.g. using masks [4, 2006.01]  • characterised by the coating material (C23C 14/04 takes precedence) [4, 2006.01]  • Oxides (C23C 14/10 takes precedence) [4, 2006.01]  • Glass or silica [4, 2006.01]	16/00 16/00 16/01 16/02 16/04 16/06 16/08 16/10 16/12 16/14	Chemical coating by decomposition of gaseous compounds, without leaving reaction products of surface material in the coating, i.e. chemical vapour deposition [CVD] processes (reactive sputtering or vacuum evaporation C23C 14/00) [4, 2006.01]  on temporary substrates, e.g. on substrates subsequently removed by etching [7, 2006.01]  Pretreatment of the material to be coated (C23C 16/04 takes precedence) [4, 2006.01]  Coating on selected surface areas, e.g. using masks [4, 2006.01]  characterised by the deposition of metallic material [4, 2006.01]  from metal halides [4, 2006.01]  peposition of chromium only [4, 2006.01]  Deposition of aluminium only [4, 2006.01]  peposition of only one other metal element [4, 2006.01]
12/02  Coating implanta 14/00  14/02 14/04 14/06 14/08 14/10 14/12	other than silicon and at least one metal element or silicon into metallic material surfaces [4, 2006.01]  • Diffusion in one step [4, 2006.01]  by vacuum evaporation, by sputtering or by ion tion [4]  Coating by vacuum evaporation, by sputtering or by ion implantation of the coating forming material [4, 2006.01]  • Pretreatment of the material to be coated (C23C 14/04 takes precedence) [4, 2006.01]  • Coating on selected surface areas, e.g. using masks [4, 2006.01]  • characterised by the coating material (C23C 14/04 takes precedence) [4, 2006.01]  • Oxides (C23C 14/10 takes precedence) [4, 2006.01]  • Glass or silica [4, 2006.01]  • Organic material [4, 2006.01]	16/00 16/00 16/01 16/02 16/04 16/06 16/08 16/10 16/12 16/14 16/16 16/18	Chemical coating by decomposition of gaseous compounds, without leaving reaction products of surface material in the coating, i.e. chemical vapour deposition [CVD] processes (reactive sputtering or vacuum evaporation C23C 14/00) [4, 2006.01]  on temporary substrates, e.g. on substrates subsequently removed by etching [7, 2006.01]  Pretreatment of the material to be coated (C23C 16/04 takes precedence) [4, 2006.01]  Coating on selected surface areas, e.g. using masks [4, 2006.01]  characterised by the deposition of metallic material [4, 2006.01]  from metal halides [4, 2006.01]  Deposition of chromium only [4, 2006.01]  Deposition of only one other metal element [4, 2006.01]  from metal carbonyl compounds [4, 2006.01]  from metallo-organic compounds [4, 2006.01]
12/02  Coating implanta  14/00  14/02  14/04  14/06  14/08  14/10  14/12  14/14	other than silicon and at least one metal element or silicon into metallic material surfaces [4, 2006.01]  • Diffusion in one step [4, 2006.01]  by vacuum evaporation, by sputtering or by ion tion [4]  Coating by vacuum evaporation, by sputtering or by ion implantation of the coating forming material [4, 2006.01]  • Pretreatment of the material to be coated (C23C 14/04 takes precedence) [4, 2006.01]  • Coating on selected surface areas, e.g. using masks [4, 2006.01]  • characterised by the coating material (C23C 14/04 takes precedence) [4, 2006.01]  • Oxides (C23C 14/10 takes precedence) [4, 2006.01]  • Glass or silica [4, 2006.01]  • Organic material [4, 2006.01]  • Metallic material, boron or silicon [4, 2006.01]	16/00 16/00 16/01 16/02 16/04 16/06 16/08 16/10 16/12 16/14 16/16 16/18 16/20	Chemical coating by decomposition of gaseous compounds, without leaving reaction products of surface material in the coating, i.e. chemical vapour deposition [CVD] processes (reactive sputtering or vacuum evaporation C23C 14/00) [4, 2006.01]  on temporary substrates, e.g. on substrates subsequently removed by etching [7, 2006.01]  Pretreatment of the material to be coated (C23C 16/04 takes precedence) [4, 2006.01]  Coating on selected surface areas, e.g. using masks [4, 2006.01]  characterised by the deposition of metallic material [4, 2006.01]  from metal halides [4, 2006.01]  Deposition of chromium only [4, 2006.01]  Deposition of only one other metal element [4, 2006.01]  from metal carbonyl compounds [4, 2006.01]  from metallo-organic compounds [4, 2006.01]  Deposition of aluminium only [4, 2006.01]
12/02  Coating implanta 14/00  14/02 14/04 14/06 14/08 14/10 14/12	other than silicon and at least one metal element or silicon into metallic material surfaces [4, 2006.01]  • Diffusion in one step [4, 2006.01]  by vacuum evaporation, by sputtering or by ion tion [4]  Coating by vacuum evaporation, by sputtering or by ion implantation of the coating forming material [4, 2006.01]  • Pretreatment of the material to be coated (C23C 14/04 takes precedence) [4, 2006.01]  • Coating on selected surface areas, e.g. using masks [4, 2006.01]  • characterised by the coating material (C23C 14/04 takes precedence) [4, 2006.01]  • Oxides (C23C 14/10 takes precedence) [4, 2006.01]  • Glass or silica [4, 2006.01]  • Organic material [4, 2006.01]	16/00 16/00 16/01 16/02 16/04 16/06 16/08 16/10 16/12 16/14 16/16 16/18 16/20 16/22	Chemical coating by decomposition of gaseous compounds, without leaving reaction products of surface material in the coating, i.e. chemical vapour deposition [CVD] processes (reactive sputtering or vacuum evaporation C23C 14/00) [4, 2006.01]  on temporary substrates, e.g. on substrates subsequently removed by etching [7, 2006.01]  Pretreatment of the material to be coated (C23C 16/04 takes precedence) [4, 2006.01]  Coating on selected surface areas, e.g. using masks [4, 2006.01]  characterised by the deposition of metallic material [4, 2006.01]  from metal halides [4, 2006.01]  peposition of chromium only [4, 2006.01]  peposition of only one other metal element [4, 2006.01]  from metal carbonyl compounds [4, 2006.01]  from metallo-organic compounds [4, 2006.01]  characterised by the deposition of inorganic material, other than metallic material [4, 2006.01]
12/02  Coating implanta  14/00  14/02  14/04  14/06  14/08  14/10  14/12  14/14  14/16  14/18	other than silicon and at least one metal element or silicon into metallic material surfaces [4, 2006.01]  • Diffusion in one step [4, 2006.01]  by vacuum evaporation, by sputtering or by ion tion [4]  Coating by vacuum evaporation, by sputtering or by ion implantation of the coating forming material [4, 2006.01]  • Pretreatment of the material to be coated (C23C 14/04 takes precedence) [4, 2006.01]  • Coating on selected surface areas, e.g. using masks [4, 2006.01]  • characterised by the coating material (C23C 14/04 takes precedence) [4, 2006.01]  • Oxides (C23C 14/10 takes precedence) [4, 2006.01]  • Glass or silica [4, 2006.01]  • Organic material [4, 2006.01]  • Metallic material, boron or silicon [4, 2006.01]  • on metallic substrates or on substrates of boron or silicon [4, 2006.01]	16/00  16/00  16/01  16/02  16/04  16/06  16/08  16/10  16/12  16/14  16/16  16/18  16/20  16/22  16/24	Chemical coating by decomposition of gaseous compounds, without leaving reaction products of surface material in the coating, i.e. chemical vapour deposition [CVD] processes (reactive sputtering or vacuum evaporation C23C 14/00) [4, 2006.01]  on temporary substrates, e.g. on substrates subsequently removed by etching [7, 2006.01]  Pretreatment of the material to be coated (C23C 16/04 takes precedence) [4, 2006.01]  Coating on selected surface areas, e.g. using masks [4, 2006.01]  characterised by the deposition of metallic material [4, 2006.01]  from metal halides [4, 2006.01]  Deposition of chromium only [4, 2006.01]  Deposition of only one other metal element [4, 2006.01]  from metal carbonyl compounds [4, 2006.01]  from metallo-organic compounds [4, 2006.01]  hold provided the deposition of inorganic material, other than metallic material [4, 2006.01]
12/02  Coating implanta 14/00  14/02  14/04  14/06  14/08  14/10  14/12  14/14  14/16	other than silicon and at least one metal element or silicon into metallic material surfaces [4, 2006.01]  • Diffusion in one step [4, 2006.01]  by vacuum evaporation, by sputtering or by ion tion [4]  Coating by vacuum evaporation, by sputtering or by ion implantation of the coating forming material [4, 2006.01]  • Pretreatment of the material to be coated (C23C 14/04 takes precedence) [4, 2006.01]  • Coating on selected surface areas, e.g. using masks [4, 2006.01]  • characterised by the coating material (C23C 14/04 takes precedence) [4, 2006.01]  • Oxides (C23C 14/10 takes precedence) [4, 2006.01]  • Glass or silica [4, 2006.01]  • Organic material [4, 2006.01]  • Metallic material, boron or silicon [4, 2006.01]  • on metallic substrates or on substrates of boron or silicon [4, 2006.01]	16/00 16/00 16/01 16/02 16/04 16/06 16/08 16/10 16/12 16/14 16/16 16/18 16/20 16/22	Chemical coating by decomposition of gaseous compounds, without leaving reaction products of surface material in the coating, i.e. chemical vapour deposition [CVD] processes (reactive sputtering or vacuum evaporation C23C 14/00) [4, 2006.01]  on temporary substrates, e.g. on substrates subsequently removed by etching [7, 2006.01]  Pretreatment of the material to be coated (C23C 16/04 takes precedence) [4, 2006.01]  Coating on selected surface areas, e.g. using masks [4, 2006.01]  characterised by the deposition of metallic material [4, 2006.01]  from metal halides [4, 2006.01]  peposition of chromium only [4, 2006.01]  peposition of only one other metal element [4, 2006.01]  from metal carbonyl compounds [4, 2006.01]  from metallo-organic compounds [4, 2006.01]  characterised by the deposition of inorganic material, other than metallic material [4, 2006.01]

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14/24

14/26

14/28

14/30

• Vacuum evaporation [4, 2006.01]

precedence) [4, 2006.01]

source [4, 2006.01]

• by resistance or inductive heating of the

by wave energy or particle radiation (C23C 14/32-C23C 14/48 take

• • • by electron bombardment **[4, 2006.01]** 

16/28

16/30

16/32

16/34

16/36

Deposition of only one other non-metal

solutions, e.g. borides, carbides,

Deposition of compounds, mixtures or solid

3

element **[4, 2006.01]** 

nitrides [4, 2006.01]

• Carbides [4, 2006.01]

• Nitrides [4, 2006.01]

• • • Carbo-nitrides [4, 2006.01]

16/38	• • • Borides [4, 2006.01]	18/16	• by reduction or substitution, i.e. electroless plating
16/40	• • • Oxides [4, 2006.01]	10/10	(C23C 18/54 takes precedence) [4, 2006.01]
16/42	• • • Silicides [4, 2006.01]	18/18	<ul> <li>Pretreatment of the material to be coated [4, 2006.01]</li> </ul>
16/44	<ul> <li>characterised by the method of coating (C23C 16/04 takes precedence) [4, 2006.01]</li> </ul>	18/20	• • • of organic surfaces, e.g. resins [4, 2006.01]
16/442	<ul> <li>using fluidised bed processes [7, 2006.01]</li> </ul>	18/22	• • • • Roughening, e.g. by etching [4, 2006.01]
16/448	<ul> <li>characterised by the method used for generating</li> </ul>	18/24	• • • • using acid aqueous solutions [4, 2006.01]
10/440	reactive gas streams, e.g. by evaporation or	18/26	• • • • using organic liquids [4, 2006.01]
	sublimation of precursor materials [7, 2006.01]	18/28	• • • • Sensitising or activating [4, 2006.01]
16/452	• • • by activating reactive gas streams before	18/30	• • • • • Activating [4, 2006.01]
	introduction into the reaction chamber, e.g. by	18/31	<ul> <li>Coating with metals [5, 2006.01]</li> </ul>
	ionization or by addition of reactive	18/32	<ul> <li>Coating with one of iron, cobalt or nickel;</li> </ul>
16/450	species [7, 2006.01]		Coating with mixtures of phosphorus or boron
16/453	<ul> <li>passing the reaction gases through burners or torches, e.g. atmospheric pressure CVD</li> </ul>		with one of these metals <b>[4, 5, 2006.01]</b>
	(C23C 16/513 takes precedence; for flame or	18/34	• • • using reducing agents [4, 5, 2006.01]
	plasma spraying of coating material in the molten	18/36	• • • • using hypophosphites [4, 5, 2006.01]
	state C23C 4/00) [7, 2006.01]	18/38	• • • Coating with copper [4, 5, 2006.01]
16/455	characterised by the method used for introducing	18/40 18/42	<ul><li>• • using reducing agents [4, 5, 2006.01]</li><li>• • Coating with noble metals [4, 5, 2006.01]</li></ul>
	gases into the reaction chamber or for modifying gas flows in the reaction chamber [7, 2006.01]	18/44	• • • • using reducing agents [4, 5, 2006.01]
16/458	<ul> <li>characterised by the method used for supporting</li> </ul>	18/48	<ul> <li>Coating with alloys [4, 5, 2006.01]</li> </ul>
10/ 430	substrates in the reaction chamber [7, 2006.01]	18/50	• • with alloys based on iron, cobalt or nickel
16/46	characterised by the method used for heating the	10/00	(C23C 18/32 takes precedence) <b>[4, 5, 2006.01]</b>
	substrate (C23C 16/48, C23C 16/50 take	18/52	<ul> <li>using reducing agents for coating with metallic</li> </ul>
	precedence) [4, 2006.01]		material not provided for in a single one of groups
16/48	• by irradiation, e.g. photolysis, radiolysis, particle	40/54	C23C 18/32-C23C 18/50 <b>[4, 2006.01]</b>
16/50	radiation [4, 2006.01]  • using electric discharges [4, 2006.01]	18/54	<ul> <li>Contact plating, i.e. electroless electrochemical plating [4, 2006.01]</li> </ul>
16/503	• • using dc or ac discharges [7, 2006.01]		plating [4, 2000.01]
16/505	• • using radio frequency discharges [7, 2006.01]	20/00	Chemical coating by decomposition of either solid
16/507	• • using external electrodes, e.g. in tunnel type		compounds or suspensions of the coating forming
	reactors [7, 2006.01]		compounds, without leaving reaction products of surface material in the coating [4, 2006.01]
16/509	• • • using internal electrodes [7, 2006.01]		
16/511	• • using microwave discharges [7, 2006.01]		Note(s) [4]
16/513	• • • using plasma jets [7, 2006.01]		This group covers also suspensions containing non-
16/515	• • using pulsed discharges [7, 2006.01]		reactive liquids and reactive solid particles.
16/517	<ul> <li>using a combination of discharges covered by two or more of groups C23C 16/503-</li> </ul>		
	C23C 16/515 <b>[7, 2006.01]</b>	20/02	• Coating with metallic material [4, 2006.01]
16/52	Controlling or regulating the coating	20/04	• • with metals [4, 2006.01]
	process [4, 2006.01]	20/06	Coating with inorganic material, other than metallic
16/54	<ul> <li>Apparatus specially adapted for continuous</li> </ul>		material [4, 2006.01]
40/50	coating [4, 2006.01]	20/08	• • with compounds, mixtures or solid solutions, e.g.
16/56	• After-treatment [4, 2006.01]		borides, carbides, nitrides [4, 2006.01]
18/00	Chemical coating by decomposition of either liquid	22/00	Chemical surface treatment of metallic material by
	compounds or solutions of the coating forming		reaction of the surface with a reactive liquid, leaving
	compounds, without leaving reaction products of		reaction products of surface material in the coating,
	surface material in the coating; Contact plating [4, 2006.01]		e.g. conversion coatings, passivation of metals [4, 2006.01]
	Note(s) [4]		Note(s) [4]
	This group <u>covers</u> also suspensions containing reactive		1. This group <u>covers</u> also suspensions containing
18/02	<ul><li>liquids and non-reactive solid particles.</li><li>by thermal decomposition [4, 2006.01]</li></ul>		reactive liquids and non-reactive solid particles.  2. Rejuvenating of the bath is classified in the
18/04	<ul> <li>Pretreatment of the material to be coated</li> </ul>		appropriate place for the specific bath
10/04	(C23C 18/06 takes precedence) [ <b>4, 2006.01</b> ]		composition.
18/06	<ul> <li>Coating on selected surface areas, e.g. using masks [4, 2006.01]</li> </ul>		Note(s) [4]
18/08	<ul> <li>characterised by the deposition of metallic material [4, 2006.01]</li> </ul>		In groups C23C 22/02-C23C 22/86, the last place priority rule is applied, i.e. at each hierarchical level, in
18/10	• • Deposition of aluminium only [4, 2006.01]		the absence of an indication to the contrary,
18/12	<ul> <li>characterised by the deposition of inorganic</li> </ul>	22.422	classification is made in the last appropriate place.
	material other than metallic material [4, 2006.01]	22/02	• using non-aqueous solutions [4, 2006.01]
18/14	<ul> <li>Decomposition by irradiation, e.g. photolysis, particle radiation [4, 2006.01]</li> </ul>	22/03	containing phosphorus compounds [4, 2006.01]

22/04			
	<ul> <li>containing hexavalent chromium compounds [4, 2006.01]</li> </ul>	22/56	• • • Treatment of aluminium or alloys based thereon [4, 5, 2006.01]
22/05	• using aqueous solutions [5, 2006.01]	22/57	• • • Treatment of magnesium or alloys based
22/06	<ul> <li>using aqueous acidic solutions with pH &lt;</li> <li>[4, 5, 2006.01]</li> </ul>	22/58	thereon <b>[4, 5, 2006.01]</b> • • • • Treatment of other metallic
22/07	• • • containing phosphates [4, 5, 2006.01]		material <b>[4, 5, 2006.01]</b>
22/08	• • • Orthophosphates [4, 5, 2006.01]	22/60	<ul> <li>using alkaline aqueous solutions with pH &gt;</li> </ul>
22/10	• • • • containing oxidants [4, 5, 2006.01]		8 <b>[4, 5, 2006.01]</b>
22/12	• • • • containing zinc cations [4, 5, 2006.01]	22/62	<ul> <li>Treatment of iron or alloys based</li> </ul>
22/13	• • • • containing also nitrate or nitrite		thereon <b>[4, 5, 2006.01]</b>
	anions [4, 5, 2006.01]	22/63	<ul> <li>• Treatment of copper or alloys based thereon [4, 5, 2006.01]</li> </ul>
22/14	• • • • • containing also chlorate anions [4, 5, 2006.01]	22/64	• • • Treatment of refractory metals or alloys based thereon [4, 5, 2006.01]
22/16	• • • • • containing also peroxy- compounds [4, 5, 2006.01]	22/66	• • • Treatment of aluminium or alloys based
22/17	• • • • • containing also organic acids [4, 5, 2006.01]	22/67	thereon [4, 5, 2006.01]  • • • with solutions containing hexavalent
22/18	• • • containing manganese		chromium [4, 5, 2006.01]
22/20	cations <b>[4, 5, 2006.01]</b> • • • • containing aluminium	22/68	• • using aqueous solutions with pH between 6 and 8 [4, 5, 2006.01]
	cations [4, 5, 2006.01]	22/70	<ul> <li>using melts [4, 2006.01]</li> </ul>
22/22	• • • containing alkaline earth metal	22/72	<ul> <li>Treatment of iron or alloys based</li> </ul>
	cations [4, 5, 2006.01]		thereon <b>[4, 2006.01]</b>
22/23	• • • Condensed phosphates [4, 5, 2006.01]	22/73	<ul> <li>characterised by the process [4, 2006.01]</li> </ul>
22/24	• containing hexavalent chromium	22/74	<ul> <li>for obtaining burned-in conversion</li> </ul>
	compounds [4, 5, 2006.01]		coatings [4, 2006.01]
22/26	• • containing also organic	22/76	<ul> <li>Applying the liquid by spraying [4, 2006.01]</li> </ul>
	compounds [4, 5, 2006.01]	22/77	<ul> <li>Controlling or regulating of the coating</li> </ul>
22/27	• • • • • Acids [4, 5, 2006.01]		process [4, 2006.01]
22/28	• • • • Macromolecular	22/78	• Pretreatment of the material to be coated <b>[4, 2006.01]</b>
	compounds <b>[4, 5, 2006.01]</b>	22/80	<ul> <li>with solutions containing titanium or zirconium</li> </ul>
22/30	• • containing also trivalent		compounds <b>[4, 2006.01]</b>
	chromium <b>[4, 5, 2006.01]</b>	22/82	<ul> <li>After-treatment [4, 2006.01]</li> </ul>
22/32	• • containing also pulverulent	22/83	<ul> <li>Chemical after-treatment [4, 2006.01]</li> </ul>
	metals <b>[4, 5, 2006.01]</b>	22/84	• • Dyeing [4, 2006.01]
22/33	• • • containing also phosphates [4, 5, 2006.01]	22/86	• Regeneration of coating baths [4, 2006.01]
22/34	• • containing fluorides or complex		
	fluorides <b>[4, 5, 2006.01]</b>	24/00	Coating starting from inorganic powder (spraying of
22/36	• • • containing also phosphates [4, 5, 2006.01]		the coating material in molten state C23C 4/00; solid
22/37	<ul> <li>containing also hexavalent chromium</li> </ul>	24/02	state diffusion C23C 8/00-C23C 12/00) <b>[4, 2006.01]</b>
	compounds [4, 5, 2006.01]	24/02	<ul> <li>by application of pressure only [4, 2006.01]</li> </ul>
22/38			T . 11 1 C
	• • • containing also	24/04	Impact or kinetic deposition of      Impact of Management of Manage
	phosphates <b>[4, 5, 2006.01]</b>		particles <b>[4, 2006.01]</b>
22/40	phosphates [4, 5, 2006.01]  • • • containing molybdates, tungstates or	24/04	
	phosphates [4, 5, 2006.01]  • • • containing molybdates, tungstates or vanadates [4, 5, 2006.01]		<ul> <li>particles [4, 2006.01]</li> <li>Compressing powdered coating material, e.g. by milling [4, 2006.01]</li> <li>by application of heat or pressure and heat</li> </ul>
22/42	phosphates [4, 5, 2006.01]  • • containing molybdates, tungstates or vanadates [4, 5, 2006.01]  • • containing also phosphates [4, 5, 2006.01]	24/06	<ul> <li>particles [4, 2006.01]</li> <li>Compressing powdered coating material, e.g. by milling [4, 2006.01]</li> </ul>
	phosphates [4, 5, 2006.01]  • • containing molybdates, tungstates or vanadates [4, 5, 2006.01]  • • containing also phosphates [4, 5, 2006.01]  • containing also hexavalent chromium	24/06	<ul> <li>particles [4, 2006.01]</li> <li>Compressing powdered coating material, e.g. by milling [4, 2006.01]</li> <li>by application of heat or pressure and heat</li> </ul>
22/42 22/43	phosphates [4, 5, 2006.01]  • • containing molybdates, tungstates or vanadates [4, 5, 2006.01]  • • containing also phosphates [4, 5, 2006.01]  • containing also hexavalent chromium compounds [4, 5, 2006.01]	24/06 24/08	<ul> <li>particles [4, 2006.01]</li> <li>Compressing powdered coating material, e.g. by milling [4, 2006.01]</li> <li>by application of heat or pressure and heat (C23C 24/04 takes precedence) [4, 2006.01]</li> </ul>
22/42	phosphates [4, 5, 2006.01]  • • containing molybdates, tungstates or vanadates [4, 5, 2006.01]  • • containing also phosphates [4, 5, 2006.01]  • • containing also hexavalent chromium compounds [4, 5, 2006.01]  • • containing also fluorides or complex	24/06 24/08 24/10	<ul> <li>particles [4, 2006.01]</li> <li>Compressing powdered coating material, e.g. by milling [4, 2006.01]</li> <li>by application of heat or pressure and heat (C23C 24/04 takes precedence) [4, 2006.01]</li> <li>with intermediate formation of a liquid phase in the layer [4, 2006.01]</li> </ul>
22/42 22/43 22/44	phosphates [4, 5, 2006.01]  • • containing molybdates, tungstates or vanadates [4, 5, 2006.01]  • • containing also phosphates [4, 5, 2006.01]  • • containing also hexavalent chromium compounds [4, 5, 2006.01]  • • containing also fluorides or complex fluorides [4, 5, 2006.01]	24/06 24/08	<ul> <li>particles [4, 2006.01]</li> <li>Compressing powdered coating material, e.g. by milling [4, 2006.01]</li> <li>by application of heat or pressure and heat (C23C 24/04 takes precedence) [4, 2006.01]</li> <li>with intermediate formation of a liquid phase in the layer [4, 2006.01]</li> <li>Coating not provided for in groups C23C 2/00-</li> </ul>
22/42 22/43 22/44 22/46	phosphates [4, 5, 2006.01]  • • containing molybdates, tungstates or vanadates [4, 5, 2006.01]  • • containing also phosphates [4, 5, 2006.01]  • • containing also hesavalent chromium compounds [4, 5, 2006.01]  • • containing also fluorides or complex fluorides [4, 5, 2006.01]  • containing oxalates [4, 5, 2006.01]	24/06 24/08 24/10 <b>26/00</b>	<ul> <li>particles [4, 2006.01]</li> <li>Compressing powdered coating material, e.g. by milling [4, 2006.01]</li> <li>by application of heat or pressure and heat (C23C 24/04 takes precedence) [4, 2006.01]</li> <li>with intermediate formation of a liquid phase in the layer [4, 2006.01]</li> <li>Coating not provided for in groups C23C 2/00-C23C 24/00 [4, 2006.01]</li> </ul>
22/42 22/43 22/44 22/46 22/47	phosphates [4, 5, 2006.01]  • • containing molybdates, tungstates or vanadates [4, 5, 2006.01]  • • containing also phosphates [4, 5, 2006.01]  • • containing also hexavalent chromium compounds [4, 5, 2006.01]  • • containing also fluorides or complex fluorides [4, 5, 2006.01]  • containing oxalates [4, 5, 2006.01]  • containing also phosphates [4, 5, 2006.01]	24/06 24/08 24/10	<ul> <li>particles [4, 2006.01]</li> <li>Compressing powdered coating material, e.g. by milling [4, 2006.01]</li> <li>by application of heat or pressure and heat (C23C 24/04 takes precedence) [4, 2006.01]</li> <li>with intermediate formation of a liquid phase in the layer [4, 2006.01]</li> <li>Coating not provided for in groups C23C 2/00-</li> </ul>
22/42 22/43 22/44 22/46	phosphates [4, 5, 2006.01]  • • • containing molybdates, tungstates or vanadates [4, 5, 2006.01]  • • • containing also phosphates [4, 5, 2006.01]  • • • containing also hexavalent chromium compounds [4, 5, 2006.01]  • • • containing also fluorides or complex fluorides [4, 5, 2006.01]  • • • containing oxalates [4, 5, 2006.01]  • • • containing also phosphates [4, 5, 2006.01]  • • not containing phosphates, hexavalent	24/06 24/08 24/10 26/00 26/02	<ul> <li>particles [4, 2006.01]</li> <li>Compressing powdered coating material, e.g. by milling [4, 2006.01]</li> <li>by application of heat or pressure and heat (C23C 24/04 takes precedence) [4, 2006.01]</li> <li>with intermediate formation of a liquid phase in the layer [4, 2006.01]</li> <li>Coating not provided for in groups C23C 2/00-C23C 24/00 [4, 2006.01]</li> <li>applying molten material to the substrate [4, 2006.01]</li> </ul>
22/42 22/43 22/44 22/46 22/47	phosphates [4, 5, 2006.01]  • • • containing molybdates, tungstates or vanadates [4, 5, 2006.01]  • • • containing also phosphates [4, 5, 2006.01]  • • • containing also hexavalent chromium compounds [4, 5, 2006.01]  • • • containing also fluorides or complex fluorides [4, 5, 2006.01]  • • • containing oxalates [4, 5, 2006.01]  • • • containing also phosphates [4, 5, 2006.01]  • • not containing phosphates, hexavalent chromium compounds, fluorides or complex	24/06 24/08 24/10 <b>26/00</b>	<ul> <li>particles [4, 2006.01]</li> <li>Compressing powdered coating material, e.g. by milling [4, 2006.01]</li> <li>by application of heat or pressure and heat (C23C 24/04 takes precedence) [4, 2006.01]</li> <li>with intermediate formation of a liquid phase in the layer [4, 2006.01]</li> <li>Coating not provided for in groups C23C 2/00-C23C 24/00 [4, 2006.01]</li> <li>applying molten material to the substrate [4, 2006.01]</li> <li>Coating for obtaining at least two superposed</li> </ul>
22/42 22/43 22/44 22/46 22/47	phosphates [4, 5, 2006.01]  • • • containing molybdates, tungstates or vanadates [4, 5, 2006.01]  • • • containing also phosphates [4, 5, 2006.01]  • • • containing also hexavalent chromium compounds [4, 5, 2006.01]  • • • containing also fluorides or complex fluorides [4, 5, 2006.01]  • • • containing oxalates [4, 5, 2006.01]  • • • containing also phosphates [4, 5, 2006.01]  • • not containing phosphates, hexavalent chromium compounds, fluorides or complex fluorides, molybdates, tungstates, vanadates or	24/06 24/08 24/10 26/00 26/02	<ul> <li>particles [4, 2006.01]</li> <li>Compressing powdered coating material, e.g. by milling [4, 2006.01]</li> <li>by application of heat or pressure and heat (C23C 24/04 takes precedence) [4, 2006.01]</li> <li>with intermediate formation of a liquid phase in the layer [4, 2006.01]</li> <li>Coating not provided for in groups C23C 2/00-C23C 24/00 [4, 2006.01]</li> <li>applying molten material to the substrate [4, 2006.01]</li> <li>Coating for obtaining at least two superposed coatings either by methods not provided for in a</li> </ul>
22/42 22/43 22/44 22/46 22/47	phosphates [4, 5, 2006.01]  • • • containing molybdates, tungstates or vanadates [4, 5, 2006.01]  • • • containing also phosphates [4, 5, 2006.01]  • • • containing also hexavalent chromium compounds [4, 5, 2006.01]  • • • containing also fluorides or complex fluorides [4, 5, 2006.01]  • • • containing oxalates [4, 5, 2006.01]  • • • containing also phosphates [4, 5, 2006.01]  • • not containing phosphates, hexavalent chromium compounds, fluorides or complex fluorides, molybdates, tungstates, vanadates or oxalates [4, 5, 2006.01]	24/06 24/08 24/10 26/00 26/02	<ul> <li>particles [4, 2006.01]</li> <li>Compressing powdered coating material, e.g. by milling [4, 2006.01]</li> <li>by application of heat or pressure and heat (C23C 24/04 takes precedence) [4, 2006.01]</li> <li>with intermediate formation of a liquid phase in the layer [4, 2006.01]</li> <li>Coating not provided for in groups C23C 2/00-C23C 24/00 [4, 2006.01]</li> <li>applying molten material to the substrate [4, 2006.01]</li> <li>Coating for obtaining at least two superposed</li> </ul>
22/42 22/43 22/44 22/46 22/47 22/48	phosphates [4, 5, 2006.01]  • • • containing molybdates, tungstates or vanadates [4, 5, 2006.01]  • • • containing also phosphates [4, 5, 2006.01]  • • • containing also hexavalent chromium compounds [4, 5, 2006.01]  • • • containing also fluorides or complex fluorides [4, 5, 2006.01]  • • • containing oxalates [4, 5, 2006.01]  • • • containing also phosphates [4, 5, 2006.01]  • • not containing phosphates, hexavalent chromium compounds, fluorides or complex fluorides, molybdates, tungstates, vanadates or	24/06 24/08 24/10 26/00 26/02	<ul> <li>particles [4, 2006.01]</li> <li>Compressing powdered coating material, e.g. by milling [4, 2006.01]</li> <li>by application of heat or pressure and heat (C23C 24/04 takes precedence) [4, 2006.01]</li> <li>with intermediate formation of a liquid phase in the layer [4, 2006.01]</li> <li>Coating not provided for in groups C23C 2/00-C23C 24/00 [4, 2006.01]</li> <li>applying molten material to the substrate [4, 2006.01]</li> <li>Coating for obtaining at least two superposed coatings either by methods not provided for in a single one of main groups C23C 2/00-C23C 26/00, or</li> </ul>
22/42 22/43 22/44 22/46 22/47 22/48	phosphates [4, 5, 2006.01]  containing molybdates, tungstates or vanadates [4, 5, 2006.01]  containing also phosphates [4, 5, 2006.01]  containing also hexavalent chromium compounds [4, 5, 2006.01]  containing also fluorides or complex fluorides [4, 5, 2006.01]  containing oxalates [4, 5, 2006.01]  containing also phosphates [4, 5, 2006.01]  not containing phosphates, hexavalent chromium compounds, fluorides or complex fluorides, molybdates, tungstates, vanadates or oxalates [4, 5, 2006.01]  Treatment of iron or alloys based	24/06 24/08 24/10 26/00 26/02	<ul> <li>particles [4, 2006.01]</li> <li>Compressing powdered coating material, e.g. by milling [4, 2006.01]</li> <li>by application of heat or pressure and heat (C23C 24/04 takes precedence) [4, 2006.01]</li> <li>with intermediate formation of a liquid phase in the layer [4, 2006.01]</li> <li>Coating not provided for in groups C23C 2/00-C23C 24/00 [4, 2006.01]</li> <li>applying molten material to the substrate [4, 2006.01]</li> <li>Coating for obtaining at least two superposed coatings either by methods not provided for in a single one of main groups C23C 2/00-C23C 26/00, or by combinations of methods provided for in</li> </ul>
22/42 22/43 22/44 22/46 22/47 22/48	phosphates [4, 5, 2006.01]  containing molybdates, tungstates or vanadates [4, 5, 2006.01]  containing also phosphates [4, 5, 2006.01]  containing also hexavalent chromium compounds [4, 5, 2006.01]  containing also fluorides or complex fluorides [4, 5, 2006.01]  containing oxalates [4, 5, 2006.01]  containing also phosphates [4, 5, 2006.01]  not containing phosphates, hexavalent chromium compounds, fluorides or complex fluorides, molybdates, tungstates, vanadates or oxalates [4, 5, 2006.01]  Treatment of iron or alloys based thereon [4, 5, 2006.01]	24/06 24/08 24/10 <b>26/00</b> 26/02 <b>28/00</b>	<ul> <li>particles [4, 2006.01]</li> <li>Compressing powdered coating material, e.g. by milling [4, 2006.01]</li> <li>by application of heat or pressure and heat (C23C 24/04 takes precedence) [4, 2006.01]</li> <li>with intermediate formation of a liquid phase in the layer [4, 2006.01]</li> <li>Coating not provided for in groups C23C 2/00-C23C 24/00 [4, 2006.01]</li> <li>applying molten material to the substrate [4, 2006.01]</li> <li>Coating for obtaining at least two superposed coatings either by methods not provided for in a single one of main groups C23C 2/00-C23C 26/00, or by combinations of methods provided for in subclasses C23C and C25D [4, 2006.01]</li> </ul>
22/42 22/43 22/44 22/46 22/47 22/48	phosphates [4, 5, 2006.01]  containing molybdates, tungstates or vanadates [4, 5, 2006.01]  containing also phosphates [4, 5, 2006.01]  containing also hexavalent chromium compounds [4, 5, 2006.01]  containing also fluorides or complex fluorides [4, 5, 2006.01]  containing oxalates [4, 5, 2006.01]  containing also phosphates [4, 5, 2006.01]  not containing phosphates, hexavalent chromium compounds, fluorides or complex fluorides, molybdates, tungstates, vanadates or oxalates [4, 5, 2006.01]  Treatment of iron or alloys based thereon [4, 5, 2006.01]  Treatment of copper or alloys based	24/06 24/08 24/10 <b>26/00</b> 26/02 <b>28/00</b>	<ul> <li>particles [4, 2006.01]</li> <li>Compressing powdered coating material, e.g. by milling [4, 2006.01]</li> <li>by application of heat or pressure and heat (C23C 24/04 takes precedence) [4, 2006.01]</li> <li>with intermediate formation of a liquid phase in the layer [4, 2006.01]</li> <li>Coating not provided for in groups C23C 2/00-C23C 24/00 [4, 2006.01]</li> <li>applying molten material to the substrate [4, 2006.01]</li> <li>Coating for obtaining at least two superposed coatings either by methods not provided for in a single one of main groups C23C 2/00-C23C 26/00, or by combinations of methods provided for in subclasses C23C and C25D [4, 2006.01]</li> <li>only coatings of metallic material [4, 2006.01]</li> </ul>
22/42 22/43 22/44 22/46 22/47 22/48 22/50 22/52	phosphates [4, 5, 2006.01]  containing molybdates, tungstates or vanadates [4, 5, 2006.01]  containing also phosphates [4, 5, 2006.01]  containing also hexavalent chromium compounds [4, 5, 2006.01]  containing also fluorides or complex fluorides [4, 5, 2006.01]  containing oxalates [4, 5, 2006.01]  containing also phosphates [4, 5, 2006.01]  not containing phosphates, hexavalent chromium compounds, fluorides or complex fluorides, molybdates, tungstates, vanadates or oxalates [4, 5, 2006.01]  Treatment of iron or alloys based thereon [4, 5, 2006.01]  Treatment of copper or alloys based thereon [4, 5, 2006.01]	24/06 24/08 24/10 26/00 26/02 28/00	<ul> <li>particles [4, 2006.01]</li> <li>Compressing powdered coating material, e.g. by milling [4, 2006.01]</li> <li>by application of heat or pressure and heat (C23C 24/04 takes precedence) [4, 2006.01]</li> <li>with intermediate formation of a liquid phase in the layer [4, 2006.01]</li> <li>Coating not provided for in groups C23C 2/00-C23C 24/00 [4, 2006.01]</li> <li>applying molten material to the substrate [4, 2006.01]</li> <li>Coating for obtaining at least two superposed coatings either by methods not provided for in a single one of main groups C23C 2/00-C23C 26/00, or by combinations of methods provided for in subclasses C23C and C25D [4, 2006.01]</li> <li>only coatings of metallic material [4, 2006.01]</li> <li>only coatings of inorganic non-metallic material [4, 2006.01]</li> </ul>
22/42 22/43 22/44 22/46 22/47 22/48 22/50 22/52	phosphates [4, 5, 2006.01]  containing molybdates, tungstates or vanadates [4, 5, 2006.01]  containing also phosphates [4, 5, 2006.01]  containing also hexavalent chromium compounds [4, 5, 2006.01]  containing also fluorides or complex fluorides [4, 5, 2006.01]  containing oxalates [4, 5, 2006.01]  containing oxalates [4, 5, 2006.01]  not containing phosphates, hexavalent chromium compounds, fluorides or complex fluorides, molybdates, tungstates, vanadates or oxalates [4, 5, 2006.01]  Treatment of iron or alloys based thereon [4, 5, 2006.01]  Treatment of copper or alloys based thereon [4, 5, 2006.01]  Treatment of zinc or alloys based	24/06 24/08 24/10 <b>26/00</b> 26/02 <b>28/00</b>	<ul> <li>particles [4, 2006.01]</li> <li>Compressing powdered coating material, e.g. by milling [4, 2006.01]</li> <li>by application of heat or pressure and heat (C23C 24/04 takes precedence) [4, 2006.01]</li> <li>with intermediate formation of a liquid phase in the layer [4, 2006.01]</li> <li>Coating not provided for in groups C23C 2/00-C23C 24/00 [4, 2006.01]</li> <li>applying molten material to the substrate [4, 2006.01]</li> <li>Coating for obtaining at least two superposed coatings either by methods not provided for in a single one of main groups C23C 2/00-C23C 26/00, or by combinations of methods provided for in subclasses C23C and C25D [4, 2006.01]</li> <li>only coatings of metallic material [4, 2006.01]</li> <li>only coatings of inorganic non-metallic material [4, 2006.01]</li> <li>Coating with metallic material characterised only by</li> </ul>
22/42 22/43 22/44 22/46 22/47 22/48 22/50 22/52 22/53	phosphates [4, 5, 2006.01]  containing molybdates, tungstates or vanadates [4, 5, 2006.01]  containing also phosphates [4, 5, 2006.01]  containing also hexavalent chromium compounds [4, 5, 2006.01]  containing also fluorides or complex fluorides [4, 5, 2006.01]  containing oxalates [4, 5, 2006.01]  containing oxalates [4, 5, 2006.01]  not containing phosphates, hexavalent chromium compounds, fluorides or complex fluorides, molybdates, tungstates, vanadates or oxalates [4, 5, 2006.01]  Treatment of iron or alloys based thereon [4, 5, 2006.01]  Treatment of copper or alloys based thereon [4, 5, 2006.01]  Treatment of zinc or alloys based thereon [4, 5, 2006.01]	24/06 24/08 24/10 26/00 26/02 28/00	<ul> <li>particles [4, 2006.01]</li> <li>Compressing powdered coating material, e.g. by milling [4, 2006.01]</li> <li>by application of heat or pressure and heat (C23C 24/04 takes precedence) [4, 2006.01]</li> <li>with intermediate formation of a liquid phase in the layer [4, 2006.01]</li> <li>Coating not provided for in groups C23C 2/00-C23C 24/00 [4, 2006.01]</li> <li>applying molten material to the substrate [4, 2006.01]</li> <li>Coating for obtaining at least two superposed coatings either by methods not provided for in a single one of main groups C23C 2/00-C23C 26/00, or by combinations of methods provided for in subclasses C23C and C25D [4, 2006.01]</li> <li>only coatings of metallic material [4, 2006.01]</li> <li>only coatings of inorganic non-metallic material [4, 2006.01]</li> <li>Coating with metallic material characterised only by the composition of the metallic material, i.e. not</li> </ul>
22/42 22/43 22/44 22/46 22/47 22/48 22/50 22/52 22/53	phosphates [4, 5, 2006.01]  containing molybdates, tungstates or vanadates [4, 5, 2006.01]  containing also phosphates [4, 5, 2006.01]  containing also hexavalent chromium compounds [4, 5, 2006.01]  containing also fluorides or complex fluorides [4, 5, 2006.01]  containing oxalates [4, 5, 2006.01]  containing oxalates [4, 5, 2006.01]  not containing phosphates, hexavalent chromium compounds, fluorides or complex fluorides, molybdates, tungstates, vanadates or oxalates [4, 5, 2006.01]  Treatment of iron or alloys based thereon [4, 5, 2006.01]  Treatment of copper or alloys based thereon [4, 5, 2006.01]  Treatment of zinc or alloys based thereon [4, 5, 2006.01]  Treatment of refractory metals or alloys	24/06 24/08 24/10 26/00 26/02 28/00	<ul> <li>particles [4, 2006.01]</li> <li>Compressing powdered coating material, e.g. by milling [4, 2006.01]</li> <li>by application of heat or pressure and heat (C23C 24/04 takes precedence) [4, 2006.01]</li> <li>with intermediate formation of a liquid phase in the layer [4, 2006.01]</li> <li>Coating not provided for in groups C23C 2/00-C23C 24/00 [4, 2006.01]</li> <li>applying molten material to the substrate [4, 2006.01]</li> <li>Coating for obtaining at least two superposed coatings either by methods not provided for in a single one of main groups C23C 2/00-C23C 26/00, or by combinations of methods provided for in subclasses C23C and C25D [4, 2006.01]</li> <li>only coatings of metallic material [4, 2006.01]</li> <li>only coatings of inorganic non-metallic material [4, 2006.01]</li> <li>Coating with metallic material characterised only by</li> </ul>

IPC (2024.01), Section C 5

#### C23D ENAMELLING OF, OR APPLYING A VITREOUS LAYER TO, METALS

## Subclass index

TREATMENT PRIOR TO ENAMELLING	1/00, 3/00
ENAMELLING	5/00-11/00
AFTER-TREATMENT	13/00, 15/00, 17/00

#### 1/00 Melting or fritting the enamels; Apparatus or furnaces therefor [1, 2006.01]

1/02 · Granulating the melt; Drying the granules [1, 2006.01]

### **Coating with the enamels**

3/00 Chemical treatment of the metal surfaces prior to coating [1, 2006.01]

#### 5/00 Coating with enamels or vitreous layers [1, 4, 2006.01]

5/02 • by wet methods [1, 2006.01]

5/04 • by dry methods [1, 2006.01]

5/06 producing designs or letters [1, 2006.01]

5/08 Applying enamels non-uniformly over the surface [1, 2006.01]

### 7/00 Treating the coatings, e.g. drying before burning [1, 2006.01]

## **Firing the enamels**

9/00 Ovens specially adapted for firing enamels [1, 2006.01]

9/02 • Non-electric muffle furnaces [1, 2006.01]

9/04 • Non-electric tunnel ovens [1, 2006.01]

9/06 • Electric furnaces [1, 2006.01]

therefor [1, 2006.01]

9/08 • Supporting devices for burning-bars [1, 2006.01] • Loading or unloading devices [1, 2006.01]

11/00 Continuous processes for firing enamels; Apparatus

After-treatment

9/10

13/00 After-treatment of the enamelled articles [1, 2006.01]

13/02 Removing defects by local re-melting of the enamel; Adjusting the shape **[1, 2006.01]** 

15/00 Joining enamelled articles to other enamelled articles by processes involving an enamelling step [1, 2006.01]

17/00 **De-enamelling [1, 2006.01]** 

C23F NON-MECHANICAL REMOVAL OF METALLIC MATERIAL FROM SURFACES (working of metal by electro-erosion B23H; desurfacing by applying flames B23K 7/00; working metal by laser beam B23K 26/00); INHIBITING CORROSION OF METALLIC MATERIAL; INHIBITING INCRUSTATION IN GENERAL (treating metal surfaces or coating of metals by electrolysis or electrophoresis C25D, C25F); MULTI-STEP PROCESSES FOR SURFACE TREATMENT OF METALLIC MATERIAL INVOLVING AT LEAST ONE PROCESS PROVIDED FOR IN CLASS C23 AND AT LEAST ONE PROCESS COVERED BY SUBCLASS C21D OR C22F OR CLASS C25 [4]

## Note(s)

- This subclass <u>covers</u> inhibiting corrosion or incrustation in general, whether of or on metallic or non-metallic surfaces, subject to Note (2) below.
- This subclass does not cover:
  - protective layers or coating compositions or methods of applying them; these are classified in the appropriate places, e.g. B05, B44, C09D, C10M, C23C;
  - mechanical devices or constructional features of particular articles for inhibiting incrustation; these are classified in the appropriate places, e.g. in pipes or pipe fittings F16L 58/00;
  - articles characterised by being made of materials selected for their properties of resistance to corrosion or incrustation; these are classified in the appropriate places, e.g. turbine blades F01D 5/28.

### **Subclass index**

ETCHING, BRIGHTENING, COMPOSITIONS THEREFOR	1/00, 3/00
OTHER REMOVING OF METALLIC MATERIAL	4/00
INHIBITING CORROSION OR INCRUSTATION	11/00-15/00
MULTI-STEP SURFACE TREATMENTS	17/00

1/00 **Etching metallic material by chemical** means [1, 2, 2006.01]

1/02 • Local etching [1, 2006.01] 1/04 • • Chemical milling [1, 2006.01]

1/06 • Sharpening files **[1, 2006.01]** 

1/08	Apparatus, e.g. for photomechanical printing		Note(s)
1/10	<ul><li>surfaces [1, 2006.01]</li><li>Etching compositions (C23F 1/44 takes precedence) [4, 2006.01]</li></ul>		In groups C23F 11/12-C23F 11/173, the last place priority rule is applied, i.e. at each hierarchical level, in
1/12	<ul> <li>Gaseous compositions [4, 2006.01]</li> </ul>		the absence of an indication to the contrary, a compound
1/14	<ul> <li>Aqueous compositions [4, 2006.01]</li> </ul>	11/12	<ul><li>is classified in the last appropriate place.</li><li>• Oxygen-containing compounds [1, 2006.01]</li></ul>
1/16	• • • Acidic compositions (C23F 1/42 takes	11/12	• • Nitrogen-containing compounds [1, 2006.01]
1, 10	precedence) [4, 2006.01]	11/14	• • • Sulfur-containing compounds [1, 2006.01]
1/18	• • • for etching copper or alloys	11/167	<ul> <li>Phosphorus-containing compounds [4, 2006.01]</li> </ul>
	thereof <b>[4, 2006.01</b> ]	11/10/	• • • Macromolecular compounds [4, 2006.01]
1/20	• • • • for etching aluminium or alloys thereof [4, 2006.01]	11/1/3	• using inorganic inhibitors [1, 2006.01]
1/22	• • • for etching magnesium or alloys thereof [4, 2006.01]	13/00	Inhibiting corrosion of metals by anodic or cathodic protection [1, 2006.01]
1/24	• • • • for etching silicon or germanium [4, 2006.01]	13/02	cathodic; Selection of conditions, parameters or procedures for cathodic protection, e.g. of electrical
1/26	• • • for etching refractory metals [4, 2006.01]		conditions <b>[5, 2006.01]</b>
1/28	• • • for etching iron group metals [4, 2006.01]	13/04	Controlling or regulating desired
1/30	• • • for etching other metallic		parameters <b>[5, 2006.01]</b>
1/32	material <b>[4, 2006.01]</b> • • • Alkaline compositions (C23F 1/42 takes	13/06	<ul> <li>Constructional parts, or assemblies of cathodic- protection apparatus [5, 2006.01]</li> </ul>
	precedence) [4, 2006.01]	13/08	<ul> <li>• Electrodes specially adapted for inhibiting</li> </ul>
1/34	• • • for etching copper or alloys thereof [4, 2006.01]		corrosion by cathodic protection; Manufacture thereof; Conducting electric current
1/36	• • • for etching aluminium or alloys	12/10	thereto [5, 2006.01]
4 /00	thereof [4, 2006.01]	13/10	• • • Electrodes characterised by the structure (C23F 13/16 takes precedence) <b>[5, 2006.01]</b>
1/38 1/40	<ul> <li>• • • for etching refractory metals [4, 2006.01]</li> <li>• • • for etching other metallic</li> </ul>	13/12	• • • Electrodes characterised by the material (C23F 13/16 takes precedence) [5, 2006.01]
1/42	material [4, 2006.01]  • • containing a dispersed water-immiscible liquid [4, 2006.01]	13/14	• • • • • Material for sacrificial anodes [5, 2006.01]
1/44	Compositions for etching metallic material from a metallic material substrate of different	13/16	• • • Electrodes characterised by the combination of the structure and the material <b>[5, 2006.01]</b>
	composition [4, 2006.01]	13/18	• • • • Means for supporting electrodes [5, 2006.01]
1/46	• Regeneration of etching compositions [4, 2006.01]	13/20	• • • Conducting electric current to electrodes [5, 2006.01]
<b>3/00</b> 3/02	<ul><li>Brightening metals by chemical means [1, 2, 2006.01]</li><li>Light metals [1, 2006.01]</li></ul>	13/22	• • • Monitoring arrangements therefor [5, 2006.01]
3/03	<ul> <li>with acidic solutions [4, 2006.01]</li> </ul>		
3/04	<ul> <li>Heavy metals [1, 2006.01]</li> </ul>	14/00	Inhibiting incrustation in apparatus for heating
3/06	• • with acidic solutions <b>[4, 2006.01]</b>		<b>liquids for physical or chemical purposes</b> (adding scale preventives or removers to water
4/00	Processes for removing metallic material from		C02F 5/00) <b>[1, 2, 2006.01]</b>
	surfaces, not provided for in group C23F 1/00 or	14/02	<ul> <li>by chemical means [1, 2006.01]</li> </ul>
	C23F 3/00 [4, 2006.01]	45 (00	
4/02	• by evaporation <b>[4, 2006.01]</b>	15/00	Other methods of preventing corrosion or
4/04	• by physical dissolution [4, 2006.01]		incrustation [1, 2006.01]
11/00	Inhibiting corrosion of metallic material by applying inhibitors to the surface in danger of corrosion or adding them to the corrosive agent [1, 2006.01]	17/00	Multi-step processes for surface treatment of metallic material involving at least one process provided for in class C23 and at least one process covered by subclass C21D or C22F or class C25 (coating for
11/02	• in air or gases by adding vapour phase inhibitors [1, 2006.01]		obtaining at least two superposed coatings either by methods not provided for in a single one of main groups
11/04	• in markedly acid liquids [1, 2006.01]		C23C 2/00-C23C 26/00, or by combinations of methods
11/06	• in markedly alkaline liquids [1, 2006.01]		provided for in subclasses C23C and C25D,
11/08	• in other liquids [1, 2006.01]		C23C 28/00) [1, 4, 2006.01]
11/10	• • using organic inhibitors [1, 2006.01]		
C23G	CLEANING OR DEGREASING OF METALLIC ELECTROLYSIS	MATERIA	L BY CHEMICAL METHODS OTHER THAN
1/00	Cleaning or pickling metallic material with solutions	1/04	• • using inhibitors [1, 2006.01]
1/00	or molten salts (with organic solvents	1/04	• • • organic inhibitors [1, 2006.01]
	C23G 5/02) [1, 2006.01]	1/08	• • Iron or steel [1, 2006.01]
			, -,

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1/02 • with acid solutions **[1, 2006.01]** 

1/10

• Iron or steel [1, 2006.01]• Other heavy metals [1, 2006.01]

1/12 1/14 1/16 1/18 1/19 1/20 1/22 1/24 1/26 1/30 1/32 1/34 1/36 3/00	<ul> <li>Light metals [1, 2006.01]</li> <li>with alkaline solutions [1, 2006.01]</li> <li>using inhibitors [1, 2006.01]</li> <li>Organic inhibitors [1, 2006.01]</li> <li>Iron or steel [4, 2006.01]</li> <li>Other heavy metals [1, 4, 2006.01]</li> <li>Light metals [1, 2006.01]</li> <li>with neutral solutions [1, 2006.01]</li> <li>using inhibitors [1, 2006.01]</li> <li>with molten salts [1, 2006.01]</li> <li>using inhibitors [1, 2006.01]</li> <li>Light metals [1, 2006.01]</li> <li>Regeneration of waste pickling liquors [1, 2006.01]</li> </ul> Apparatus for cleaning or pickling metallic material (with organic solvents C23G 5/04) [1, 2006.01]	3/04 5/00 5/02 5/024 5/028 5/032 5/036 5/04	<ul> <li>for cleaning pipes [1, 2006.01]</li> <li>Cleaning or de-greasing metallic material by other methods; Apparatus for cleaning or de-greasing metallic material with organic solvents [1, 2006.01]</li> <li>Note(s) [4]</li> <li>In groups C23G 5/02-C23G 5/06, the last place priority rule is applied, i.e. at each hierarchical level, in the absence of an indication to the contrary, classification is made in the last appropriate place.</li> <li>using organic solvents [1, 2006.01]</li> <li>containing hydrocarbons [4, 2006.01]</li> <li>containing halogenated hydrocarbons [4, 2006.01]</li> <li>containing oxygen-containing compounds [4, 2006.01]</li> <li>having also nitrogen [4, 2006.01]</li> <li>Apparatus [1, 2006.01]</li> </ul>
3/00			3 3 1
3/02	<ul> <li>for cleaning wires, strips, filaments continuously [1, 2006.01]</li> </ul>	5/06	• using emulsions <b>[4, 2006.01]</b>